SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

SDLS003 D2632. JANUARY 1981 - REVISED MARCH 1988 SN54LS590, SN54LS591...J OR W PACKAGE

- 8-Bit Counter with Register
- Parallel Register Outputs

schematics of inputs and outputs

- Choice of 3-State ('LS590) or Open-Collector ('LS591) Register Outputs
- Guaranteed Counter Frequency: DC to 20 MHz

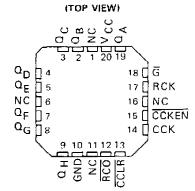
description

These devices each contain an 8-bit binary counter that feeds an 8 bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register. The binary counter features a direct clear input CCLR and a count enable input CCKEN. For cascading, a ripple carry output RCO is provided. Expansion is easily accomplished for two stages by connecting RCO of the first stage to CCKEN of the second stage. Cascading for larger count chains can be accomplished by connecting RCO of each stage to CCK of the following stage.

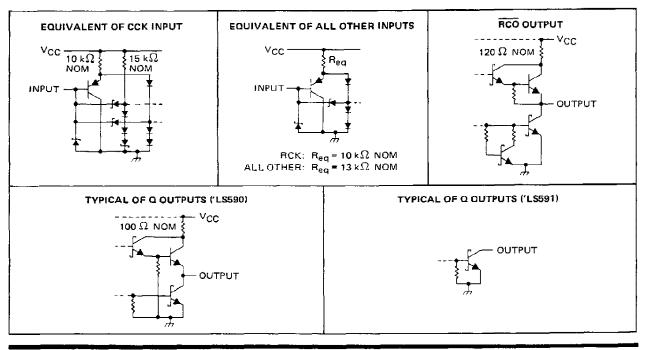
Both the counter and register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the counter state will always be one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

SN74LS590, SN74L	S591	N PACKAGE
(TOP		
ов []		Vcc
QC []2	15	0 _A
Q _D []₃	14 🗍	G
QE ∐4	13	RCK
QF [5	12	CCKEN
Q G 🗍 6	11	сск
₽н[]7	10	CCLR
GND 🛛	9	RCO

SN54LS590, SN54LS591 . . . FK PACKAGE



NC - No internal connection

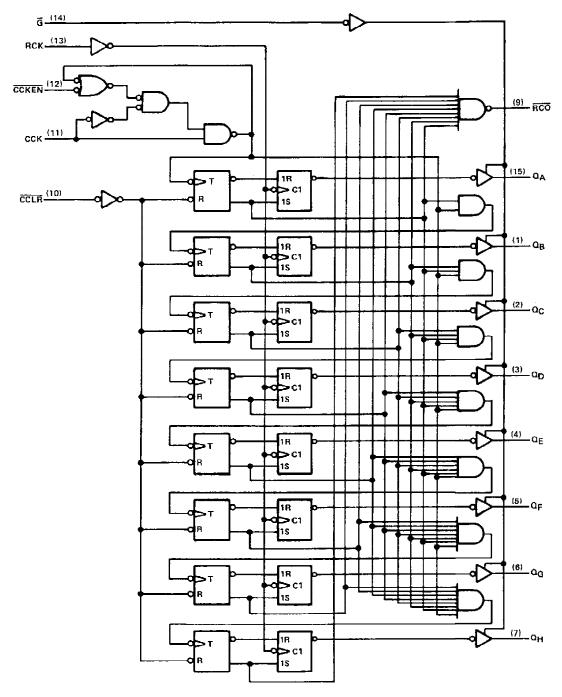


PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standerd warranty. Production processing does not necessarily include testing of all parameters.



SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

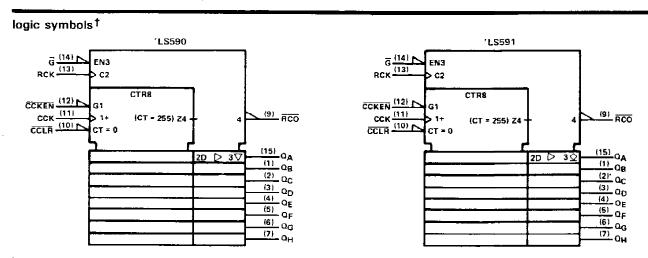
logic diagram (positive logic)



Pin numbers shown are for J, N and W packages.



SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS



 $^\dagger These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for J, N, and W packages.$

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7V
Input voltage	
Off-state output voltage	
Operating free-air temperature range: SN54LS590, SN54LS591	
SN74LS590, SN74LS591	\dots 0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

			:	SN54LS		SN74LS'				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.7			0.8	V	
Voн	High-level output voltage	Q, 'LS591 only	1		5.5	1		5.5	V	
Inu	High lovel autout ourset	RCO	1		1			- 1		
юн	High-level output current	Q, (L\$590 only	1		- 1			- 2.6	mA	
	Low-level output current	RCO			8			16	6	
IOL		Q			12			24	mA	
fock	Counter clock frequency		0	-	20	0		20	MHz	
frck	Register clock frequency		0		25	0		25	MHz	
^t w(CCK)	Duration of counter clock pu	lse	25			25			пѕ	
tw(CCLR)	Duration of counter clear puls	se	20			20			ns	
^t w(RCK)	Duration of register clock pul	se	20			20			<u>пs</u>	
		CCKEN low before CCK1	20			20				
t _{su}	Setup time	CCLR inactive before CCK1	20			20		<u> </u>	ns	
		CCK before RCK f (see Note 2)	40	*		40			1	
th	Hold time	CCKEN low after CCK1	0			0			ns	
TA	Operating free-air temperature	e	- 55		125	0		70	°C	

NOTE 2: This setup time ensures the register will see stable data from the counter outputs. The clocks may be tied together in which case the register state will be one clock pulse behind the counter.



SN54LS590, SN54LS591, SN74LS590, SN74LS591 8 BIT BINARY COUNTERS WITH OUTPUT REGISTERS

			I	EST CONDITIO			SN54LS	,		SN74LS		
F	PARAMETE	R	Т	MIN	TYP‡	MAX	MIN	TYP‡	MAX			
Vik			Vcc = MIN,	1 ₁ = - 18 mA				- 1.5			- 1.5	v
	11.55.00.0)/ - MIN		¹ OH = - 1 mA	2.4	3.2					
∨он	1LS590 C	!	V _{CC} = MIN,	v H - zv,	¹ OH = - 2.6 mA	1			2,4	3.1		V
	RCO		VIL = MAX		^I OH = - 1 mA	2.4	3.2		2.4	3.2		_
юн	'L\$591 C)	V _{CC} = MIN, V _{IL} - MAX	V _{IH} = 2 V,	V _{OH} = 5.5 V,			Q.1			0.1	mA
					1 _{0L} = 12 mA	•	0.25	0.4		0.25	0.4	
	a		V _{CC} = MIN,	V _{IH} = 2 V,	1 _{0L} = 24 mA	+				0.35	5 0.5 V	
VOL	RCO		VIL = MAX		IOL = 8 mA	1	0,25	0.4		0.25	0.4	v
	RCU				I _{OL} = 16 mA					0.35	0.5	0.5
Iоzн	'LS590 C	1	V _{CC} = MAX, V _O = 2.7 V	V _{IH} = 2 V,	V _{IL} = MAX,			20			20	μA
I _{OZL}	′L\$590 C	1		V _{1H} = 2 V.	VIL = MAX,		·	- 20			- 20	μA
	i		V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mΑ
<u>і</u> н			V _{CC} = MAX,					20	T		20	μA
	сск							- 0,8	1		- 0.8	mA
ΊL	All other	5	V _{CC} = MAX,	V ₁ = 0.4 V	$V_{1} = 0.4 V$			- 0.2		•	- 0.2	
	1L\$590 C	1	11 . KGA V	<u> </u>		- 30		- 130	- 30		- 130	mA
los§	RCO		Vcc÷MAX,	v0-0 v		- 20		- 100	- 20		- 100	ША
		1ссн					33	55		33	55	
	'LS590	ICCL	V _{CC} = MAX,		uts grounded,		44	65		44		mA
lcc		lccz	All possible inp	uts grounded,			46	65		46	65	
	'L\$591	USEDI CCH A		en .		L	35	55		35		
	LS591 ICCL]	r			42	65		42	65	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions, ‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ § Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second,

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM	то			'LS590)		UNIT			
	(INPUT)	(OUTPUT)	TEST COND	DITIONS	MIN	TYP	MAX	MIN	түр	MAX	UNIT
fmax	RCK	a	$R_{L} = 667 \Omega,$	C _L = 45 pF	20	35		20	35		MHz
^t PLH	CCKT	RCO	R _L = 1 kΩ,	C _L = 30 pF	Ī	14	22		16	24	ns
^t PHL	CCKt	RCO				20	30		25	38	ns
tPLH	CCLR	RCO				30	45		32	48	ns
^t PLH	RCK1	Q		С _L = 45 рF	İ	12	18		25	38	ns
tPHL	RCKt					22	33		28	42	ns
tpzh	Ğı	<u>a</u>	$R_L = 667 \Omega$,		-	25	38				ns
tpzl	Ğ∔	<u>a</u>				30	45				ns
t _{PHZ}	<u>G</u> t	Q		2 5 5		20	30				ns
^t PLZ	Gt	<u>a</u>	RL=667Ω.	CL = 5 pF		25	38				ns
tpLH	Gt	<u> </u>			1				34	50	ns
tPHL I	Ğ↓		R _L = 667 Ω,	C _L = 45 pF	· · · · · ·		-		32	48	ាទ

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87517012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87517012A SNJ54LS 590FK	Samples
5962-8751701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J	Samples
5962-8751701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J	Samples
SN54LS590J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS590J	Samples
SN54LS590J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS590J	Samples
SN74LS590D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS590	Samples
SN74LS590D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS590	Samples
SN74LS590N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS590N	Samples
SN74LS590N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS590N	Samples
SN74LS590NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS590	Samples
SN74LS590NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS590	Samples
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87517012A SNJ54LS 590FK	Samples
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87517012A SNJ54LS 590FK	Samples
SNJ54LS590J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J	Samples
SNJ54LS590J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8751701EA SNJ54LS590J	Samples

PACKAGE OPTION ADDENDUM



(1) The marketing status values are defined as follows:
 ACTIVE: Product device recommended for new designs.
 LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
 NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
 PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
 OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption. **Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS590, SN74LS590 :

• Catalog : SN74LS590

• Military : SN54LS590

NOTE: Qualified Version Definitions:



- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS590NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS590NSR	SO	NS	16	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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3-Jun-2022

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-87517012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LS590D	D	SOIC	16	40	507	8	3940	4.32
SN74LS590N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS590N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS590FK	FK	LCCC	20	1	506.98	12.06	2030	NA

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



NS0016A



PACKAGE OUTLINE

SOP - 2.00 mm max height

SOP



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- Per ASME Y14.5M.
 This drawing is subject to change without notice.
 This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



NS0016A

EXAMPLE BOARD LAYOUT

SOP - 2.00 mm max height

SOP



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



NS0016A

EXAMPLE STENCIL DESIGN

SOP - 2.00 mm max height

SOP



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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